



## Material Content Data Sheet



<b>Sales Product Name</b>		SAB-C161PI-LF 3V CA		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA000097540						
<b>Package</b>		PG-TQFP-100-1		<b>Weight*</b>		680.69 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	12.734	1.87	1.87	18707	18707
leadframe	non noble metal	nickel	7440-02-0	70.395	10.34		103416	
	non noble metal	iron	7439-89-6	97.212	14.28	24.62	142813	246229
wire	noble metal	gold	7440-57-5	4.040	0.59	0.59	5936	5936
encapsulation	organic material	carbon black	1333-86-4	1.446	0.21		2124	
	plastics	epoxy resin	-	61.215	8.99		89931	
	inorganic material	silicondioxide	60676-86-0	419.348	61.62	70.82	616060	708115
leadfinish	non noble metal	tin	7440-31-5	6.201	0.91	0.91	9109	9109
plating	noble metal	silver	7440-22-4	5.282	0.78	0.78	7760	7760
glue	plastics	acrylic resin	-	0.564	0.08		829	
	noble metal	silver	7440-22-4	2.256	0.33	0.41	3315	4144
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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